

MONITORING APPARATUS AND METHOD FOR TAPE
AUTOMATED BONDING PROCESS

ABSTRACT

5 A monitoring apparatus for a tape automated bonding process, which is used to attach a plurality of flexible substrates constructed in the form of a tape to an edge of a rigid substrate, the monitoring apparatus comprises a sensor for sensing the variation of an optical signal and being moved along the edge of the rigid substrate so as to monitor the quantity of the flexible substrates according to the number of the variation of the optical signal.